**PCB Name:** <Description> **Size of PCB:** XX x YY mm

**PCB Item No:** <Item No> **No of layers:** Z

**PCB Revision:** <Revision> **Shape:**  Rectangular or square

Irregular

**Stack up and thickness:**

According to specification that can be found on the drill drawing (Gerber file).

Remove this text <Here would be a great place to define the layer stack of the board but the layer stack is intentionally left out in this template to avoid having the same information in more than one location>

**PCB requirements:**

IPC 6012 (latest revision), Class 2

UL 94V-0

UL-marked

Electrically Tested

**RoHS: Impedance:**

Yes  Yes xx Ohm acc. to drill the drawing

No  No

**Copper foil thicknesses**

**Inner layers Outer layers  
(finished copper acc. to IPC-6012, table 3-7) (finished copper acc. to IPC-6012, table 3-8)**

Weight Weight

0.5oz (18µm)  0.5oz (18µm) + plating

1oz (35µm)  1oz (35µm) + plating

2oz (70µm)  2oz (70µm) + plating

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**Solder coating / Surface finishes Electro plated gold**

LF-HASL (Lead free)  Electroplated Au (over Ni) according to ASTM B-488,

HASL purity type 1 (99.7%), hardness code C (130-200 HVN).

OSP Min thickness according to IPC-6012 table 3-2

ENIG (IPC-4552) (Ni min 2.5 μm, Au min 0.8 μm).

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**Solder Mask Top: Screenprint Top:**

No  No

Yes ->  Green  Yes ->  White

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**Solder Mask Bottom: Screenprint Bottom:**

No  No

Yes ->  Green  Yes ->  White

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